GPC 352-1

ELECTRICALLY CONDUCTIVE EPOXY ADHESIVE

DESCRIPTION: GPC 352-1 is a two part, heat curing, silver filled epoxy adhesive. System is designed to be used for making electrical and mechanical attachments on electrical components and devices. Unlike typical heat curing systems, this product always results in excellent conductivity and is less sensitive to handling and ambient conditions.

<table>
<thead>
<tr>
<th></th>
<th>Part A</th>
<th>Part B</th>
</tr>
</thead>
<tbody>
<tr>
<td>Appearance:</td>
<td>Silver</td>
<td>Light Yellow</td>
</tr>
<tr>
<td>Consistency:</td>
<td>Paste</td>
<td>Liquid</td>
</tr>
<tr>
<td>Mix Ratio (by weight):</td>
<td>100</td>
<td>13</td>
</tr>
<tr>
<td>Pot Life:</td>
<td>-----</td>
<td>&gt; 4 days</td>
</tr>
</tbody>
</table>

MIXING INSTRUCTIONS: Premix Part A in original container prior to adding curing agent. Add Part B to Part A and mix until uniform.

CURING INSTRUCTIONS: Best results are obtained when product is cured at one of the following schedules:
- 90 mins @ 80°C or
- 60 mins @ 100°C or
- 30 mins @ 125°C or
- 15 mins @ 150°C

TYPICAL CURED PROPERTIES:

- Volume Resistivity, max. (Ω-cm): 0.0005
- Silver Content (%): 73
- Water Absorption (%): < 0.06
- Tensile Strength (psi): 11,200
- Solvent Resistance: Excellent
- Solderable: No
- Specific Gravity (g/cc): 3.1

All technical information is based on data obtained by CMI personnel and is believed to be reliable. No warranty is either implied or expressed with respect to results or possible infringements on patents.

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